



PRODUCT CHANGE NOTIFICATION

PCN NUMBER: 022503

DATE: 23 July 2003

SUBJECT: AZM CHANGE NOTIFICATION REGARDING AZ10/100ELT20X (die)

TITLE: Change to smaller die area and larger wafer diameter, porting to equivalent process at different foundry and foundry location, design change to simplify 10/100 selection, design change to improve ESD

EFFECTIVE DATE: 1 August 2003

AFFECTED CHANGE CATEGORIES: Wafer diameter and process, foundry and location, die Dimensions, design changes

AFFECTED PRODUCTS: Die of AZ100ELT20, i.e., AZ10/100ELT20X

DISCLAIMER: AZM considers this change approved unless specific conditions of acceptance are provided within 30 days of receipt of this notice. To do so, please contact AZM.

DESCRIPTION AND PURPOSE: The previous foundry, AGERE, has terminated the process. AZM has ported the design to an equivalent, qualified production process at ZARLINK (formerly Plessey) in Swindon, UK, on larger diameter wafers. Additionally, AZM took the opportunity to reduce die area to an area identical to other AZM die, e.g. -16VR, -16VT, others, while providing the same pad placement coordinates. This new size also enables the use of 2x2x0.75 mm QFN packages. Additionally, AZM has attempted to improve ESD characteristics.

QUALIFICATION STATUS: Process is qualified and in production at 11 FITs (55C and 60% confidence).

ELECTRICAL CHARACTERISTICS: No changes to electrical specs are anticipated.

PACKAGE: NA